

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, May 19, 2012 03:47 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FSA2271TUMX	FSA2271TUMX	10-uMLP 1.4X1.8 (NiPdAu)			SUBCONTRACTOR	0.004	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom
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RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted
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Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC	0
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Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name 10-uMLP 1.4X1.8 (NiPdAu)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.459	Supplier		Silicon	0.459	7440-21-3	128571
Die Attach	Other Organic Materials	0.116	Supplier		Resin	0.116	54208-63-8	32493
Encapsulation	Thermoplastics	1.980	Supplier		Carbon Black	0.020	1333-86-4	5546
			Supplier		Epoxy Resin	0.396	29690-82-2	110924
			Supplier		Phenol Resin	0.099	23834-02-6	27731
			Supplier		Silica	1.465	60676-86-0	410420
Lead Frame	Other Ferrous alloys, non-stainless steels	0.932	Supplier		Copper	0.908	7440-50-8	254224
			Supplier		Iron	0.022	7439-89-6	6266
			Supplier		Phosphorus	0.001	7723-14-0	235
			Supplier		Zinc	0.001	7440-66-6	392
Plating	Precious metals	0.040	Supplier		Gold	0.001	7440-57-5	164
			B	Nickel (external applications only)	Nickel	0.036	7440-02-0	10056
			Supplier		Palladium	0.004	7440-05-3	1017
Wire Bond	Precious metals	0.047	Supplier		Gold	0.047	7440-57-5	13109